Product Change Notification: CENO-21RGMD150

Date:

27-Aug-2025

Product Category:

32-Bit Microcontrollers

Notification Subject:

CCB 7238.001 Final Notice: Qualification of palladium-coated copper with gold flash (CuPdAu) as an additional bond wire material for selected ATSAMD21xx, ATSAMC21xx, ATSAMC20xx, ATSAMDA1xx, ATSAMD20xx, ATSAML22xx, ATSAML21xx, PIC32CM2xx, PIC32CM1xx, PIC32CM3xx, PIC32CM6xx, ATSAML10xx, ATSAML11xx and PIC32CM5xx device families available in 32L and 48L VQFN (5x5x1mm and 7x7x0.9mm) packages at MMT assembly site.

Affected CPNs:

CENO-21RGMD150_Affected_CPN_08272025.pdf
CENO-21RGMD150_Affected_CPN_08272025.csv

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of palladium-coated copper with gold flash (CuPdAu) as an additional bond wire material for selected ATSAMD21xx, ATSAMC21xx, ATSAMC20xx, ATSAMDA1xx, ATSAMD20xx, ATSAML22xx, ATSAML21xx, PIC32CM2xx, PIC32CM1xx, PIC32CM3xx, PIC32CM6xx, ATSAML10xx, ATSAML11xx and PIC32CM5xx device families available in 32L and 48L VQFN (5x5x1mm and 7x7x0.9mm) packages at MMT assembly site.

Pre and Post Summary Changes:

	Pre Change	**Post Change**
Assembly Site	Microchip Technology Thailand (Branch) (MMT)	Microchip Technology Thailand

		(Branch) (MMT)	
Wire Material	Au	Au	CuPdAu
Die Attach Material	3280	QMI519 *	
Molding Compound Material	G700LTD	G700LTD	
Lead-Frame Material	C194	C194	

Note 1: **PFAS-free material.*

Note 2: **The qualification of the new PFAS-free die attach material, QMI519, was officially released via PCN #**CENO-16EGCZ399***.

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying palladium-coated copper with gold flash (CuPdAu) bond wire as an additional wire material.

Change Implementation Status: In Progress

Estimated First Ship Date: 14 November 2025 (date code: 2546)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	August 2025					**>**	**November 2025**				
Work Week	31	32	33	34	35		45	46	47	48	49
Qual Report Availability					X						
Final PCN Issue Date					X						
Estimated Implementation Date								X			

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: August 27, 2025: Issued final notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_CENO-21RGMD150-Qualification Report.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

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